# **TPAC V1 Paper**

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Abstract

ECAL, CMOS blah.

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### 1 Introduction - $\sim 2$ pages

Context of the ILC. ECAL important for hadronic jet resolution for PFA. Sampling binary RCAL.

ILC operation will consist of bunch trains, a short burst of O(1000) bunch crossings lasting O(msec), followed by a quiet period of O(sec). Data are buffered on sensor during the bunch train and read out following this during the quiet period.

## 2 Requirements - $\sim 5$ pages

#### 2.1 Electromagnetic shower properties

MIPs better measure of shower energy than deposited energy. Density of MIPs in  $500\,{\rm GeV}$  showers.

#### 2.2 ILC requirements

Pixel size. Timing. Hit rate and noise. Machine background.

#### 2.3 Others

Power.

### 3 Design - $\sim 10$ pages

#### 3.1 Overall architecture

Top-level overview.

Figure 1: Sensor overall architecture.

#### 3.2 Fabrication and INMAPS

 $0.18\,\mu\mathrm{m}$  CMOS INMAPS process.

#### 3.3 Pre-shaper pixel

Circuit, parameters.

Figure 2: Pre-shaper pixel circuit.

Mode of operation.

#### 3.4 Pre-sampler pixel

Circuit, parameters. Mode of operation. Figure 3: Pre-sampler pixel circuit.

#### 3.5 Mask and trim configuration

Operation. Load method. Readback.

#### 3.6 Data storage

Memory operation. Dead area. Memory limit.

#### 3.7 Readout

Operation of readout columns. Speed limitation.

#### 3.8 Known design issues

Details of three bugs. Crosstalk and power.

#### 3.9 DAQ system and operation

USB\_DAQ and support PCB. Bonding and yield issues. Operating parameters for all following measurements are 400 ns bunch crossings. Grounding of substrate.

### 4 Single pixel performance - $\sim 10$ pages

#### 4.1 Circuit simulation

Expected noise, gain.

Figure 4: Simulation of noise.

#### 4.2 Charge spread simulation

Charge spread. Signal size vs. position. Overall efficiency for MIP vs. threshold.

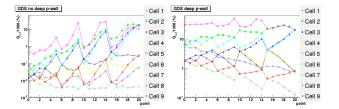


Figure 5: Simulation of charge spread for (left) no deep p-well and (right) deep p-well

Overall efficiency for MIP vs. threshold.

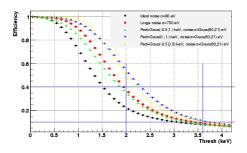


Figure 6: Simulation of efficiency vs. threshold.

### 4.3 Test pixel performance

Analogue noise,

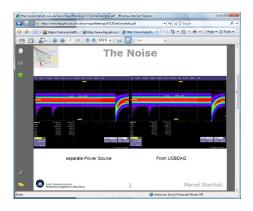


Figure 7: Test pixel noise.

gain (from laser),

Figure 8: Test pixel laser signal.

calibration of pre-samplers gain (from  $^{55}$ Fe);

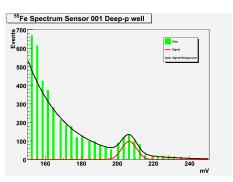
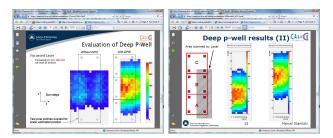


Figure 9: Test pixel  $^{55}$ Fe signal.

compared to simulation.



Laser charge spread vs. position; compared to simulation with and without deep p-well.

Figure 10: Test pixel charge spread.

#### 4.4 Bulk pedestal and noise

Analogue pedestal and noise from threshold scan.

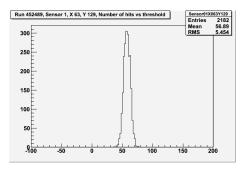


Figure 11: Typical channel threshold scan.

Pedestal and noise distributions for quadrants 0 and 1.

Figure 12: Distributions of (left) pedestals and (right) noise for quadrant 0 (solid histogram) and 1 (dashed histogram).

Uniformity vs. position.

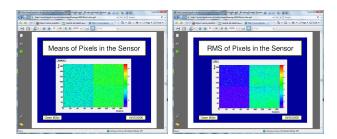


Figure 13: Two-D map of (left) pedestals and (right) noise for a typical sensor.

Effect of trim Effect of resets at start of bunch train. Effect of substrate ground.

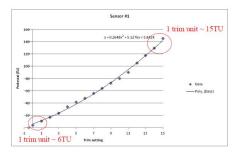


Figure 14: Typical channel trim scan.

#### 4.5 Bulk laser signal response

Measurement of laser signal.

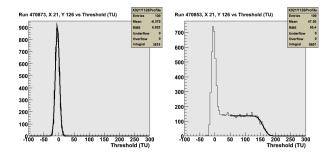


Figure 15: Threshold scan (left) without and (right) with laser.

Effect of focus and hence substrate tilt.

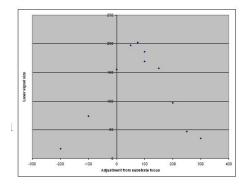


Figure 16: Signal size vs laser focus.

Optimisation of S/N with biases.

Gain (from laser),

calibration of bulk pre-samplers and pre-shapers; compared to simulation.

Laser charge spread vs. position; compared to simulation with and without deep p-well.

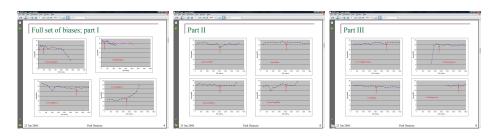


Figure 17: Laser signal/noise as a function of various bias DAC settings.

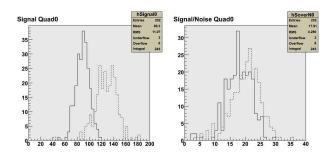


Figure 18: Laser (left) signal and (right) signal/noise for quadrants 0 (solid line) and 1 (dashed line).

Figure 19: Two-D map of laser gain for typical sensor.

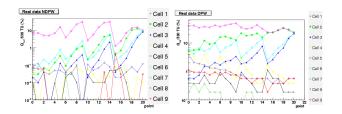


Figure 20: Charge seen at each impact point for each pixel (right) without deep p-well and (left) with deep p-well.

## 5 Sensor performance - $\sim 10$ pages

#### 5.1 Configuration load

Error rates from sensor load.

#### 5.2 Noise and crosstalk

Crosstalk;

dependence on masking, position. Single pixel plots in 4 done with only pixel studied unmasked. Possible cause of crosstalk, how to fix.

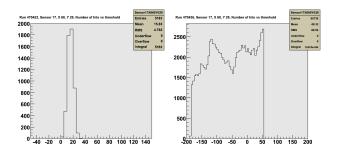


Figure 21: Effect of crosstalk on typical pixel (left) single pixel enabled (right) all pixels enabled.

Figure 22: Onset of crosstalk as number of unmasked channels increases.

#### 5.3 Hit corruption

Twinning, corruption rates using hitOverride.

#### 5.4 Source response

Efficiency vs threshold for  $^{90}$ Sr.

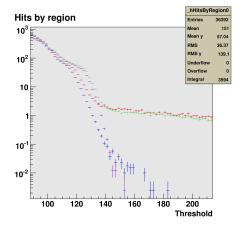


Figure 23: Rate of hits vs threshold for  $^{90}$ Sr.

Calibration peak for  ${}^{55}$ Fe).

Figure 24: Rate of hits vs threshold for  ${}^{55}$ Fe.

#### 5.5 Beam test

DESY, Dec 2007 for one week. Around 100 runs, XXXTBytes. Explain ran with no trim, crosstalk, high threshold.

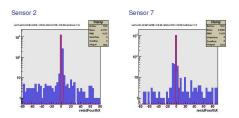


Figure 25: Residuals on inner sensors.

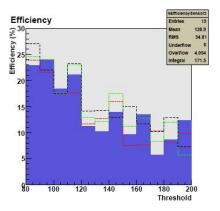


Figure 26: Efficiency vs threshold.

As a tracker; residuals.

Measure pedestal separately, correct to "real" threshold. Relative efficiency vs real threshold, comparing real threshold distribution for all and for hit pixels.

Figure 27: Distribution of real thresholds for all and hit pixels.

Figure 28: Relative efficiency vs real threshold.

#### 5.6 Cosmics

Absolute MIPS efficiency

Figure 29: Efficiency vs real threshold.

## 6 Physics performance - $\sim 5$ pages

#### 6.1 Simulation

GEANT4 and Mokka. Verified using general CALICE beam test.

#### 6.2 MIP counting

Weighting of neighbours.

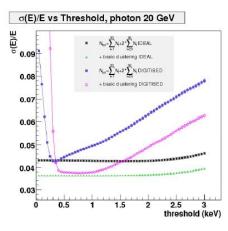


Figure 30: Effect of MIP counting.

#### 6.3 Electromagnetic shower resolution

Resolution with and without INMAPS deep p-well.

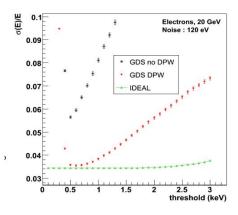


Figure 31: Resolution with and without deep p-well including MIP counting.

#### 6.4 Hadronic jet resolution

No-harm case.

Improvements.

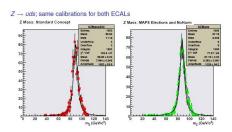


Figure 32: Hadronic jet resolution for "no-harm" case.

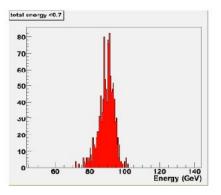


Figure 33: Hadronic jet resolution with PFA-improved algorithm.

# 7 Conclusions - $\sim 2$ pages

Proven INMAPS deep p-well. Proven pixel design adequate. Proven DECAL will work better than AECAL.

Need work on overall sensor crosstalk and trims/pedestal variations.